

**Intel[®] Server Board SE7520BD2 and
SE7520BD2D2
Memory List Test Report Summary**

Revision 55.0

July 2008

Revision History

Date	Rev	Modifications
Aug/04	.5	Preliminary Draft
Aug/04	.6	Added Samsung* 512MB part. (In shaded area)
Sept/04	1.0	Added statement "The E7520 Chipset only supports BGA DRAM module Technology for DDR333". Added Qimonda* 256MB part. Added Micron* 512MB parts. Added Smart* 1GB parts. Added Dataram* 2GB parts. (In shaded area)
Sep/04	2.0	Added Legend* 256Mb and 512MB parts. Added TRS* 512MB and 2GB parts. Added Ventura* 512MB parts. Added Micron and Smart 1GB parts. (In shaded area)
Oct/04	3.0	Added TRS, Dataram, Hynix*, Qimonda and ATP* 512MB parts. Added Legend, Kingston* and Viking* 1GB parts. Added Smart 2GB parts. (In shaded area)
Oct/04	4.0	Added Samsung and Qimonda 256MB parts. Added Qimonda, Legend and ATP 512MB parts. Added TRS, Smart, Centon*, and Dataram 1GB parts. (In shaded area)
Oct/04	5.0	Added Smart and Hynix 512MB parts. Added Smart, TRS and ATP 1GB parts. Added Ventura 2GB parts. (In shaded area)
Nov/04	6.0	Added ATP 256MB parts. Added Ventura, TRS and Hynix 1GB parts. (In shaded area)
Dec/04	7.0	Added Kingston* 2GB parts. (In shaded area)
Dec/04	8.0	Added Legacy* 1GB parts. (In shaded area)
Dec/04	9.0	Added Hynix 512MB part. Added Ventura 1GB and Viking 2GB parts. (In shaded area)
Jan/04	10.0	Added Legacy* 512MB and ATP 1GB parts. (In shaded area)
Jan/05	11.0	Added Qimonda 1GB and Smart 2GB parts. (In shaded area)
Feb/05	12.0	Added Micron 256MB part. Added Swissbit* and Micron 1GB parts. Added ATP and Dataram 2GB parts. (In shaded area)
Feb/05	13.0	Added Samsung 256MB and 512MB parts. Added Ventura 512MB parts. Added Swissbit 1GB parts. (In shaded area)
Mar/05	14.0	Added Ventura 512MB parts. Added Smart 1GB parts. Added ATP 1GB and 2GB parts. (In shaded area)
Mar/05	15.0	Added note on Lead free modules (these modules are now in bold text). Added Dane-Elec* 512MB parts. Added ATP, Ventura, Legacy and Qimonda 1GB parts. Added ATP and Qimonda 2GB parts. (In shaded area)
Apr/05	16.0	Added Dane-Elec 1GB parts. Added Micron 512MB and 1GB parts. (In shaded area)
Apr/05	17.0	Added Ventura, Simple*, Samsung and Kingston 512MB parts. Added Simple, Ventura and Wintec* 1GB parts. Added Kingston and Wintec 2GB parts. Added Micron 4GB part. (In shaded area)
May/05	18.0	Added Avant* 512MB and 1GB parts. Added Samsung 1GB part. Added Qimonda 256MB and 2GB parts. Added Micron and Hynix 512MB parts. (In shaded area)

Date	Rev	Modifications
May/05	19.0	Added Dataram 1GB parts. Added Avant 2GB parts. (In shaded area)
Jun/05	20.0	Added Samsung 512MB parts. Added Micron 1GB part. Added Qimonda and Smart 2GB parts. (In shaded area)
Jun/05	21.0	Added TRS and Wintec 512MB parts. Added Samsung 1GB and 2GB parts. Added Hynix 2GB part. (In shaded area)
July/05	22.0	Added Intel Server Board SE7250BD2D2 utilizing DDR2400 memory. Added DDR2 - Qimonda and Samsung 256MB; Hynix, Micron and Samsung 512MB; Hynix, Qimonda, Micron and Samsung 2GB modules. Added DDR1 – Samsung 512MB and 1GB modules.
Aug/05	23.0	Added Kingston, Micron, Qimonda and Samsung 512MB and 1GB parts. Added TRS and Micron 2GB parts. Hynix 1GB part. (In shaded area)
Aug/05	24.0	Added Samsung 1GB and 4GB parts. Added TRS and Legacy 2GB parts. Added Smart DDR2 1GB parts. Added Kingston, Smart and Legacy DDR2 2GB parts. Added Micron DDR2 256MB part. Added Kingston and Qimonda DDR2 512MB parts. (In shaded area)
Sept/05	25.0	Added Legacy 512MB part. Added ATP DDR2 512MB parts. Added Samsung 1GB parts. Added Viking and Samsung 2GB parts. Added Samsung DDR2 2GB part. Added ATP, Smart, and Legacy DDR2 1GB parts. (In shaded area)
Sept/05	26.0	Added Dataram, Micron and Samsung DDR 512MB part. Added Legacy DDR 1GB part. Added Micron DDR 2GB part. Added Virtium, Samsung and Kingston DDR2 1GB parts. Added Ventura DDR2 512MB part. (In shaded area)
Oct/05	27.0	Added Legend 1GB part. Added Kingston 2GB part. Added Dataram, Kingston, Smart and Ventura DDR2 1GB parts. Added Smart DDR2 2GB part. (In shaded area) Updated unleaded parts with correct shading.
Nov/05	28.0	Added Samsung 256MB parts. Added Hynix and Samsung 512MB parts. Added Legacy, Hynix, Samsung and Legend 1GB parts. Added Smart, Samsung and Hynix 2GB parts. Added Qimonda 4GB part. (In shaded area)
Nov/05	29.0	Updated two Micron 1GB parts with corrected DRAM part numbers. (in shaded area)
Dec/05	30.0	Added Legacy DDR2 512MB part. (In shaded area)
Jan/06	31.0	Added Kingston DDR2 512MB, 1GB and 2GB parts. Added ATP DDR2 512MB part. (In shaded area)
Jan/06	32.0	Added Nanya DDR2 512MB, 1GB and 2GB parts. Added Legacy DDR2 2GB part. Added Hynix DDR2 512MB & 1G parts Added Samsung DDR2 2G part. Added Samsung DDR1 256MB, 512MB, 1G & 2G parts. (In shaded area)
Feb/06	33.0	Added Kingston and Smart DDR2 1GB parts. Added Qimonda DDR1 512MB, 1G & 2G parts. Added Hynix DDR2 1G & 2G parts. (In shaded area)
Mar/06	34.0	Added Legacy, Wintec and SimpleTech DDR2 1GB parts. Added Legend DDR2 2GB part. (In shaded area)
Mar/06	35.0	Added Smart DDR2 1GB part. (In shaded area)
May/06	36.0	Qimonda name change to Qimonda effective May 1 st , 2006. (In shaded area)
June/06	37.0	Added Ventura 512MB part. Added Apacer, ATP and TRS 1GB parts. Added Kingston 1GB and 2GB parts. (In shaded area)
July/06	38.0	Added TRS 512MB part. Added TRS, Smart, and Kingston 1GB parts. Added Apacer, Kingston, and Smart 2GB parts. (In shaded area)

Date	Rev	Modifications
Aug/06	39.0	Added Dataram 512MB parts. Added Kingston 512MB and 2GB parts. (In shaded area)
Aug/06	40.0	Added Super Talent Electronics 1GB part. (In shaded area)
Oct/06	41.0	Added Super Talent Electronics and TRS 512MB parts. Added Super Talent Electronics, TRS, and Kingston 1GB parts. Added Super Talent Electronics 2GB part. (In shaded area)
Nov/06	42.0	Added Kingston 512MB, 1GB, and 2GB parts. (In shaded area)
Jan/07	43.0	Added Kingston 1GB part. Added Kingston and Smart 2GB parts. (In shaded area)
Jan/07	44.0	Added Micron 512MB and 1GB parts. Added Smart Modular Technologies 4GB part. (In shaded area)
Feb/07	45.0	Added Kingston 4GB part. Updated vendor contact information. (In shaded area)
Mar/07	46.0	Added TRS 1GB part. (In shaded area)
Mar/07	47.0	Updated contact information. Added Kingston 512MB part. (In shaded area)
May/07	48.0	Added Kingston and Netlist 2GB parts. (In shaded area)
May/07	49.0	Additional memory parts added. (In shaded area)
Nov/07	50.0	Additional memory parts added. (In shaded area)
Jan/08	51.0	Additional memory parts added. (In shaded area)
Mar/08	52.0	Additional memory parts added. (In shaded area)
May/08	53.0	Additional memory parts added. (In shaded area)
June/08	54.0	Additional memory parts added. (In shaded area)
July/08	55.0	Additional memory parts added. (In shaded area)

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The Intel® Server Board SE7520BD2 or SE7520BD2D2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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Please Note: DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each Rank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each Rank on the memory module is NOT recommended.

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1. Overview of Memory Testing

The following test processes are used to qualify Dual In-Line Memory Modules (DIMMs) for use with the Intel® Server Boards SE7520BD2 and SE7520BD2D2. Memory is a vital subsystem in a server. Intel requires that strict guidelines be met before a DIMM vendor is added to the Tested Memory List. To be included on the list as a fully supported DIMM, the memory must undergo rigorous tests to ensure that the product will perform the intended server product functions. Memory qualification for Intel server, workstation, and RAID products is performed both by Intel's Memory Validation Lab (MVL) and by an independent external test lab, Computer Memory Test Lab* (CMTL).

The Tested Memory Lists for Intel's server board, workstation board, and RAID controller products categorize memory modules as advanced tested. The advanced testing process includes a standard paper qualification and then is followed by two levels of functional testing. DIMMs that have completed and passed advanced testing are considered to be compatible with the product on which they were tested, and with the test software and operating systems that were used during the test process.

1.1 Paper Qualification

A paper qualification is performed to verify that the specifications of a given DIMM meet Intel's memory specifications for a given product. Specification criteria reviewed include: critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements.

1.2 Functional Testing

After a given DIMM passes the standard paper qualification, functionality of the DIMM is then tested with the intended Intel product. Two levels of functional testing are performed; standard and advanced.

Standard functional testing requires that the given DIMM and Intel product combination operate with no failures for a period of no less than 24 hours for both minimum and maximum DIMM configurations. Testing is performed using a Microsoft* Windows* operating system and a custom test package. The test systems operate with standard voltage at room temperature.

Advanced functional testing requires that the given DIMM and Intel product combination operate with no failures for a period of no less than 24 hours for both minimum and maximum DIMM configurations. Testing is performed with multiple operating systems and various custom test packages. Each test configuration is tested with various voltages and temperature margin conditions.

1.3 Computer Memory Test Lab*

Computer Memory Test Lab, also known as CMTL*, is a leading memory test organization responsible for testing a broad range of memory products. A memory product, which receives a "PASS" after being tested by CMTL, means it functions correctly and consumers can use the product to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with Intel supplied equipment and procedures defined by Intel's various functional testing levels.

CMTL Contact Info:

Office: (949) 716-8690
Fax: (949) 716-8691

Computer Memory Test Lab (CMTL)
24 Hammond Suite F
Irvine, CA 92618
<http://www.cmtlabs.com/>

2. Memory Subsystem

The Intel® Server Board SE7520BD2 is capable of supporting either DDR266 or DDR333 memory technologies. The Intel® Server Board SE7520BD2D2 is capable of supporting DDR2400 memory technologies.

NOTE: Industry naming conventions for equivalent memory technologies include the following:

- DDR266 = PC2100
- DDR333 = PC2700
- DDR2400 = PC23200

The following maximum memory capacities are supported based on the number of DIMM slots provided and maximum supported memory loads by the chipset:

24GB maximum capacity for DDR266

16GB maximum capacity for DDR333

16GB maximum capacity for DDR2400

The minimum memory supported with the system running in single channel memory mode is:

256MB for DDR266, DDR333 and DDR2400.

Supported DIMM capacities are as follows:

256MB, 512MB, 1GB, 2GB, and 4GB.

2.1 Memory Population

The Intel® Server Board SE7520BD2 has eight DIMM slots, or four DIMM banks. Both DIMMs in a bank should be identical (same manufacturer, CAS latency, number of rows, columns and devices, timing parameters etc.). Although DIMMs within each bank must be identical, the BIOS supports various DIMM sizes and configurations allowing the banks of memory to be different. Memory sizing and configuration is guaranteed only for qualified DIMMs approved by Intel.

Mixing of DDR266 and DDR333 DIMMs is supported between banks of memory. However, when mixing DIMM types, DDR333 will run at DDR266 speeds.

The memory controller is capable of supporting up to 4 loads per channel for DDR333. Memory technologies are classified as being either single rank or dual rank depending on the number of DRAM devices that are used on any one DIMM. A single rank DIMM is a single load device, i.e., Single Rank = 1 Load. Dual rank DIMMs are dual load devices, i.e., Dual Rank = 2 loads.

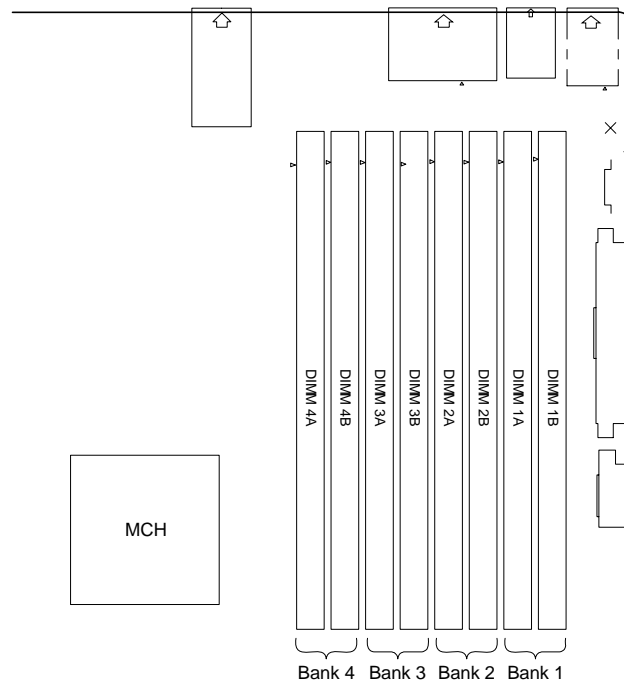


Figure 1. Identifying Banks of Memory

DDR266, DDR333 and DDR2400 DIMM population rules are as follows:

- (1) DIMM banks must be populated in order starting with the slots furthest from MCH.
- (2) Single rank DIMMs must be populated before dual rank DIMMs.
- (3) A maximum of four DIMMs can be populated when all four DIMMs are dual rank DDR333 DIMMs.

The following tables show the supported memory configurations:

- s/r = single rank
- d/r = dual rank
- E = Empty

Table 1: Supported DDR266 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	D/R	D/R	D/R
	E	D/R	D/R
	E	E	D/R
	D/R	S/R	S/R
	D/R	D/R	S/R
E	D/R	S/R	

Table 2: Supported DDR333 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	E	D/R	D/R
	E	E	D/R
	D/R	S/R	S/R
E	D/R	S/R	

Table 3: Supported DDR2400 DIMM Populations

MCH	Bank 4 – DIMMs 4A, 4B	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R	S/R
	E	E	S/R	S/R
	E	E	E	S/R
	E	E	D/R	D/R
	E	E	E	D/R
	E	D/R	S/R	S/R
E	E	D/R	S/R	

Note: On the Server Boards SE7520BD2 and SE7520BD2D2, when using all dual rank DDR333 or DDR2400 DIMMs, a total of four DIMMs can be populated. Configuring more than four dual rank DDR333 or DDR2400 DIMMs will result in the BIOS generating a memory configuration error.

2.2 Identifying “Single Rank” or “Double Ranked” DIMMs

- **x8SR** = x8 *Single-Ranked modules* - have 5 DRAMs on the front and 4 DRAMs on the back with empty spots in between the DRAM's or have 9 DRAMs on one side and none on the backside.
- **x8DR** = x8 *Double-Ranked modules* - have 9 DRAMs on each side for a total of 18 (no empty slots)
- **x4SR** = x4 *Single-Ranked modules* - have 9 DRAMs on each side for a total of 18 – and look similar to x8 Double-Ranked
- **x4DR** = x4 *Double-Ranked modules* - have 18 (stacked) DRAMs on each side for a total of 36

The following tables list the current supported memory types:

DDR266 Registered SDRAM Module Matrix						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11	Single Ranked
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10	Double Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11	Single Ranked
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11	Double Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11	Double Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12	Single Ranked
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12	Double Ranked
DDR333 Registered SDRAM Module Matrix						
Note: The E7520 Chipset only supports BGA DRAM module Technology for DDR333						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11	Single Ranked
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10	Double Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11	Single Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12	Single Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11	Double Ranked
1GB	128M x 72	1Gbit	128M x 4	9/1/4	14/2/11	Single Ranked
2GB	256M x 72	1Gbit	128M x 4	18/1/4	14/2/12	Single Ranked
2GB	256M x 72	1Gbit	128M x 8	18/2/4	14/2/11	Double Ranked
4GB	TBD	TBD	TBD	TBD	TBD	TBD

DDR2-400 Registered SDRAM Module Matrix						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	14/2/10	Single Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	14/2/11	Single Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	14/2/10	Double Ranked
1GB	128M x 72	1Gbit	128M x 8	9/1/8	14/3/10	Single Ranked
2GB	256M x 72	1Gbit	256M x 4	18/1/8	14/3/11	Single Ranked
2GB	256M x 72	1Gbit	128M x 8	18/2/8	14/3/10	Double Ranked
2GB	256M x 72	2Gbit	256M x 8	9/1/8	15/3/10	Single Ranked
4GB	512M x 72	2Gbit	256M x 8	18/2/8	15/3/10	Double Ranked
4GB	512M x 72	2Gbit	512M x 4	18/1/8	15/3/11	Single Ranked
4GB	512M x 72	4Gbit	512M x 8	9/1/8	TBD	Single Ranked

3. Tested Memory

The following tables list DIMM devices tested to be compatible with the Intel® Server Boards SE7520BD2 and SE7520BD2D2. The list of tested memory is periodically updated as qualified memory is added during the production life of the Intel product.

Intel strongly recommends the use of ECC memory in all server products.

Memory modules not listed in the following tables have not been tested for compatibility and their use with the Intel® Server Boards SE7520BD2 or SE7520BD2D2 may result in unpredictable operation and data loss.

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy. This list is subject to change without notice.

Note: This list is not intended to be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

Server Board SE7520BD2
Registered ECC, DDR266 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+Legend*	L3272YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1		(32Mx8)*9	SR	9/3/04
Micron*	MT9VDDT3272G-265G3	MT46V32M8-6T G	Micron			(32Mx8)*9	SR	1/20/05

Registered ECC, DDR333 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Micron	MT9VDDF3272G-335G3	MT46V32M8FG-6	Micron			(32Mx8)*9	SR	8/3/04
Qimonda*	HYS72D32300GB R-6-C	HYB25D256800CC-6	Qimonda			(32Mx8)*9	SR	8/30/04
Samsung*	M312L3223EG0-CB3	K4H560838E-GCB3	Samsung			(32Mx8)*9	SR	10/4/04
Qimonda	HYS72D32300GB R-6-B	HYB25D256800BC-6	Qimonda			(32Mx8)*9	SR	10/6/04
+ATP Electronics*	AB32L72V8BFB3 S	K4H560838E-GCB3 rev E	Samsung	SB184V08L 1		(32Mx8)*9	SR	10/26/04
Samsung	M312L3223EZ0-CB3	K4H560838E-ZCB3	Samsung		Yes	(32Mx8)*9	SR	2/24/05
Samsung	M312L3223EG3-CB3	K4H560838E-GCB3	Samsung			(32Mx8)*9	SR	11/15/05
Samsung	M312L3223EZ3-CB3	K4H560838E-ZCB3	Samsung		Yes	(32Mx8)*9	SR	11/15/05

Registered ECC, DDR2-400 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Qimonda	HYS72T32000HR-5-A	HYB18T256800AF5-A	Qimonda		Yes	(32Mx8)*9	SR	5/2/05
Samsung	M393T3253FG0-CCC	K4T56083QF-GCCC	Samsung			(32Mx8)*9	SR	5/24/05
Samsung	M393T3253FZ0-CCC	K4T56083QF-ZCCC	Samsung		Yes	(32Mx8)*9	SR	5/24/05
Micron	MT9HTF3272Y-40EB2	MT47H32M8BP-37E	Micron		Yes	(32Mx8)*9	SR	8/31/05
Samsung	M393T3253FG3-CCC	K4T56083QF-GCCC	Samsung			(32Mx8)*9	SR	11/4/05

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Server Board SE7520BD2
Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+Ventura Technology Group*	D52WVK42SV	K4H560838E-TCB3 rev E	Samsung	DR1G872-A		(32Mx8) *18	DR	9/2/04
+Legend	L6472YC5-PPASDD5D	K4H560438D-TCB3 rev D	Samsung	18-25141A Rev A		(64Mx4) *18	SR	8/31/04
+TRS*	TRS21151	HYB25D256400BT-7 rev B	Qimonda	M0530LA1 rev 1		(64Mx4) *18	SR	9/8/04
+TRS	TRS21152	HYB25D256800BT-7 rev B	Qimonda	M0529LA1 rev 1		(32Mx8) *18	DR	9/22/04
+Legend	L6472YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1		(32Mx8) *18	DR	10/4/04
Hynix*	HYMD264G726D4 M-H AA	HY5DU56422DT-H	Hynix			(64Mx4)*18	SR	12/22/04
Micron	MT18VDDT6472G-265G3	MT46V64M4-75 G	Micron			(32Mx8)*18	DR	4/11/05
Samsung	M312L6420ETS-CB0	K4H560438E-TCB0	Samsung			(64Mx4)*18	SR	4/13/05
Samsung	M312L6420EUS-CB0	K4H560438E-UCB0	Samsung		Yes	(64Mx4)*18	SR	4/13/05
+TRS	TRS21202	HYB25D256400CE-7 rev C	Qimonda	M0530LA1 rev 1		(64Mx4)*18	SR	6/8/05
+Legacy Electronics Inc.*	88M6JDFR-1JDG	MT46V64M4TG-75 rev C	Micron	LE18DDT18 44RRM rev B		(64Mx4)*18	SR	9/12/05

Registered, ECC, DDR333 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Qimonda	HYS72D64300GB R-6-C	HYB25D256400CC-6	Qimonda			(64Mx4) *18	SR	7/20/04
Samsung	M312L6420EG0-CB3	K4H560438E-GCB3	Samsung			(64Mx4) *18	SR	8/16/04
Micron	MT18VDDF6472G-335C1	MT46V64M4FB-6	Micron			(32Mx8) *18	DR	8/30/04
Micron	MT18VDDF6472G-335G3	4AGII D9BJR	Micron			(64Mx8)*9	SR	8/31/04
+ATP Electronics	AB64L72L4BFB3C	HYB25D256400BC-5 rev B	Qimonda	SB184L04L1		(64Mx4) *18	SR	9/14/04
Hynix	HYMD264G72DF4 N-J AA	HY5DU564220-F-J	Hynix			(64Mx4) *18	SR	9/17/04
+Dataram*	DTM63676D	HYB25D256400CC-6 rev C	Qimonda	40018A rev A		(64Mx4) *18	SR	9/20/04
Qimonda	HYS72D64320GB R-6-C	HYS72D64320GBR-6-C	Qimonda			(32Mx8) *18	DR	9/22/04
+ATP Electronics	AB64L72L4BFB3S	K4H560438E-GCB3 rev E	Samsung	SB184L04L1		(64Mx4) *18	SR	10/8/04
Qimonda	HYS72D64320GB R-6-B	HYB25D256800BC-6	Qimonda			(32Mx8) *18	DR	10/6/04

**Registered, ECC, DDR333 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+Smart Modular Technologies*	SM6472RDDR6H1 BGBC	HYB25D256400CC-6 rev C	Qimonda	184-22-2		(64Mx4) *18	SR	10/14/04
Hynix	HYMD564G72BF8 N-J AA	HY5DU12822BF-J	Hynix			(64Mx8)*9	SR	10/27/04
+Legacy Electronics Inc.	88S6JDGR-1NDG	HYB25D256400BC6 rev B	Qimonda	LE36DDF18 44RC rev B		(64Mx4) *18	SR	12/20/04
+Ventura Technology Group	D52YCK44SV	K4H560438E-GCB3 rev E	Samsung	DR1G472B		(64Mx4) *18	SR	2/10/05
Samsung	M312L6420EZ0-CB3	K4H560438E-ZCB3	Samsung		Yes	(64Mx4)*18	SR	2/24/05
+Ventura Technology Group	D52YCK44SV	K4H560438E-GCB3 rev E	Samsung	DR1G472B		(64Mx4)*18	SR	2/10/05
+Dane-Elec*	DLD333R072645H	MT46V64M4FG-5B rev G	Micron	DR1G472B		(64Mx4)*18	SR	3/1/05
+Ventura Technology Group	D52YCK44MV	MT46V64M4FG-6 rev G	Micron	DR1G472B		(64Mx4)*18	SR	3/29/05
+SimpleTech*	ST72E4K64ML-D06E	HYB25D256400CC-6 rev C	Qimonda	01269 rev A		(64Mx4)*18	SR	4/13/05
Samsung	M312L6420EUS-CB0	K4H560438E-UCB0	Samsung		Yes	(64Mx4)*18	SR	4/13/05
+Kingston*	KVR333S4R25/51 2I	HYB25D256400CC-6 rev C	Qimonda	2025161-001.B00		(64Mx4)*18	SR	4/5/05
+Avant Technology*	AVM7264R38C533 3K6-MTG	MT46V64M4FG-5B rev G	Micron	RCE0020-01 rev 1		(64Mx4)*18	SR	4/27/05
+Wintec Industries*	3C944646-L	HYB25D256400CC-5 rev C	Qimonda	DR1G472B		(64Mx4)*18	SR	6/14/05
+Kingston	KVR333S4R25/51 2I	K4H560438E-GCB3 rev E	Samsung	2025161-001.B00 na	Yes	(64Mx4)*18	SR	7/18/05
Samsung	M312L6523CZ0-CB3	K4H510838C-ZCB3	Samsung		Yes	(64Mx8)*9	SR	9/28/05
Micron	MT9VDDF6472G-335D3	MT46V64M8FG	Micron			(64Mx8)*9	SR	9/26/05
Hynix	HYMD564G726CF P8N-J	HY5DU12822CFP-J	Hynix			(64Mx8)*9	SR	10/24/05
Samsung	M312L6420EG3-CB3	K4H560438E-GCB3	Samsung			(64Mx4)*18	SR	11/15/05
Samsung	M312L6420EZ3-CB3	K4H560438E-ZCB3	Samsung		Yes	(64Mx4)*18	SR	11/15/05
Samsung	M312L6523CZ3-CB3	K4H510838C-ZCB3	Samsung		Yes	(64Mx8)*9	SR	11/15/05
Qimonda	HYS72D64301HB R-6-C	HYB25D512800CF-6	Qimonda		Yes	(64Mx8)*9	SR	1/31/06
Kingston	KVR333S4R25/51 2I	HYB25D256400CF-5 rev C	Qimonda	2025161-001.B00 na	Yes	(64Mx4)*18	SR	3/21/07

**Registered, ECC, DDR2-400 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Hynix	HYMP564R728-E3-AA	HY5PS12821-F-E3-AA	Hynix			(64Mx8)*9	SR	5/2/05
Micron	MT18HTF6472Y-40EB2	MT47H64M4BP-37E	Micron		Yes			5/2/05
Samsung	M393T6450FG0-CCC	K4T56043QF-GCCC	Samsung			(64Mx4)*18	SR	6/6/05
Samsung	M393T6450FZ0-CCC	K4T56043QF-ZCCC	Samsung		Yes	(64Mx4)*18	SR	6/6/05
Samsung	M393T6450FG0-CCC	K4T56043QF-GCCC	Samsung			(64Mx4)* 18	SR	6/6/05
Samsung	M393T6450FZ0-CCC	K4T56043QF-ZCCC	Samsung		Yes	(64Mx4)* 18	SR	6/6/05
Micron	MT9HTF6472Y-40EB2	MT47H64M8CB-5E	Micron		Yes	(64Mx8)*9	SR	7/18/05
Samsung	M393T6453FZ0-CCC	K4T56083QF-ZCCC	Samsung		Yes	(32Mx8)* 18	DR	6/27/05
Samsung	M393T6453FG0-CCC	K4T56083QF-GCCC	Samsung			(32Mx8)* 18	DR	6/27/05
Samsung	M393T6553CZ0-CCC	K4T51083QC-ZCCC	Samsung		Yes	(64Mx8)*9	SR	8/3/05
Samsung	M393T6450FZ0-CCC	K4T56043QF-ZCCC	Samsung		Yes	(64Mx4)*18	SR	8/3/05
Qimonda	HYS72T64020H R-5-A	HYB18T256800AF5-A	Qimonda		Yes	(64Mx4)*18	SR	8/3/05
+Kingston	KVR400D2S8R3 /512I	HYB18T512800AF37 rev A	Qimonda	2025263-001.C00 na		(64Mx8)*9	SR	08/10/05
Qimonda	HYS72T64001H R-5-A	HYB18T256400AF5-A	Qimonda		Yes	(64Mx4)*18	SR	8/30/05
+ATP Electronics*	AH64K72N8BHC 4S	K4T51083QC-ZCD5 rev C	Samsung	SH240N08 K1 na		(64Mx8)*9	SR	9/15/05
+Dataram	DTM63311C	K4T56043QF-(Z)GCCC rev F	Samsung	40011A rev A		(64Mx4)*18	SR	9/19/05
+Ventura Technology Group	D2-52KC53SV-333	K4T56043QF-ZCD5 rev F	Samsung	D2R472 na		(64Mx4)*18	SR	9/23/05
Samsung	M393T6450FZ3-CCC	K4T56043QF-ZCCC	Samsung		Yes	(64Mx4)*18	SR	10/24/05
Samsung	M393T6553CZ3-CCC	K4T51083QC-ZCCC	Samsung		Yes	(64Mx8)*9	SR	11/4/05
Samsung	M393T6453FG3-CCC	K4T56083QF-GCCC	Samsung			(32Mx8)*18	DR	11/4/05
Samsung	M393T6453FZ3-CCC	K4T56083QF-ZCCC	Samsung		Yes	(32Mx8)*18	DR	11/4/05
Samsung	M393T6450FG3-CCC	K4T56043QF-GCCC	Samsung			(64Mx4)*18	SR	11/4/05
+Legacy Electronics Inc.	B557K4C2AAA-50	K4T51083QC-ZCCC rev C	Samsung	LE9DD2F2 408RRA rev A		(64Mx8)*9	SR	11/14/05
+Kingston	KVR400D2S8R3 /512I	NT5TU64M8AE-37B rev A	Nanya	2025263-001.C00 na		(64Mx8)*9	SR	12/8/05

Registered, ECC, DDR2-400 DIMM Modules 512 MB Sizes (64Mx72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+ATP Electronics	AH64K72F8BH C4S	K4T51083QC-ZCD5 rev C	Samsung	SH240F08 K1 na	Yes	(64Mx8)*9	SR	12/20/05
Nanya Technology Corporation	NT512T72U89A 0BV-5A	NT5TU64M8AE-5A rev A	Nanya	NTPCB00 020P (0509) na		(64Mx8)*9	SR	1/9/06
Hynix	HYMP564R72P 8-E3	HY5PS12821FP-E3	Hynix		Yes	(64Mx8)*9	SR	12/13/05
Hynix	HYMP564R72B P8-E3	HY5PS12821BFP-E3	Hynix		Yes	(64Mx8)*9	SR	1/10/06
Ventura Technology Group	D2-52KD65SV-333	K4T51083QC-ZCD5 rev C	Samsung	D2R18A na	Yes	(64Mx8)*9	SR	05/04/06
TRS	TRS31260X	HYB18T512800AF5 rev A	Qimonda	M0551LA1 rev 1	Yes	(64Mx8)*9		6/28/06
Kingston	KVR400D2S8R 3/512I	E5108AG-5C-E rev G	Elpida	2025263-001.C00 na	Yes	(64Mx8)*9		7/13/06
Kingston	KVR400D2S8R 3/512I	E5108AG-5C-E rev G	Elpida	2025263-001.C00 na	Yes	(64Mx8)*9		7/14/06
Dataram	DTM63311D	HYB18T256400AF5 rev A	Qimonda (Infineon)	40011A rev A	Yes	(64Mx4)*18		7/17/06
Dataram	DTM63312B	NT5TU64M8AE-37B rev A	Nanya	40042A rev A	Yes	(64Mx8)*9		7/18/06
Super Talent Electronics	T400RA512/S12 TR8BHS	K4T51083QC-ZCD5 rev C	Samsung	DR20809 rev F1.01	Yes	(64Mx8)*9		8/24/06
TRS	TRS31261X	HYB18T256400AF5 rev A	Qimonda (Infineon)	M0549LA1 rev 1	Yes	(64Mx4)*18		9/5/06
TRS	TRS31275	E5108AG-5C-E rev G	Elpida	M0551LA1 rev 1	Yes	(64Mx8)*9		9/18/06
Kingston	KVR400D2S8R 3/512I	E5108AGBG-6E-E rev G	Elpida	2025263-001.C00 na	Yes	(64Mx8)*9	SR	11/8/06
Registered, ECC, DDR2-533 DIMM Modules 512 MB Sizes (64Mx72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Micron	MT9HTF6472Y-53ED4	MT47H64M4B6-37E:D	Micron		Yes	(64Mx4)*18		1/11/07

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

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Verify that the DRAM part number matches the DRAM on this list before purchasing.

Server Board SE7520BD2
Registered, ECC, DDR266 DIMM Modules
1GB Size (128M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead -Free	DRAM Organization	Rank	Date
+Legend	L1272YC5-RU1HHD5A	HY5DU12822AT-H rev A	Hyundai	DRR1U0818-A rev 1		(64Mx8)*18	DR	9/16/04
+TRS*	TRS21174	HYB25D512800AT-7 rev A	Qimonda	M0529LA1 rev 1		(64Mx8)*18	DR	9/28/04
+TRS	TRS21171	HYB25D256400BC-7 rev B	Qimonda	M0533LA1 rev 1		(64Mx4)*36	DR	10/13/04
+TRS	TRS21203	HYB25D512400BE-7 rev B	Qimonda	M0530LA1 rev 1		(128Mx4)*18	SR	10/22/04
+Ventura Technology Group	D54WYK42SV	K4H510838B-TCB3 rev B	Samsung	DR1G872-A		(64Mx8)*18	DR	11/4/04
Hynix	HYMD512G726B4M-HAA	HY5DU12422BT-H	Hynix			(128Mx4)*18	SR	11/15/04
+Swissbit*	SDR12872K1A321N-70	HYB25D256400CC-5 rev C	Qimonda	B6R404 rev 1		(64Mx4)*36	DR	2/4/05
Micron	MT18VDDT12872G-265D2	MT46V128M4TG-6T	Micron			(128Mx4)*18	SR	4/1/05
Samsung	M312L2828ET0-CB0	K4H510638E-TCB0	Samsung			(64Mx4)*36	DR	6/27/05
Samsung	M312L2828EZ0-CB0	M312L2828EZ0-CB0	Samsung		Yes	(64Mx4)*36	DR	7/25/05
Samsung	M312L2920CUS-CB0	K4H510438C-UCB0	Samsung		Yes	(128Mx4)*18	SR	9/21/05
+Legend	L1272YC5-183HDD5A	HY5DU56422AS-H rev A	Hyundai	184RL rev 3		(64Mx4)*36	DR	10/12/05
Smart Modular Technologies	SG12872RDDR308BTSC	K4H510838C-UCCC rev C	Samsung	PG52G184NEBZ6RCL rev A	Yes	(64Mx8)*18		6/14/06

Registered, ECC, DDR333 DIMM Modules
1GB Size (128M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead -Free	DRAM Organization	Rank	Date
Qimonda	HYS72D128320GBR-6-C	HYB25D256400CC-6	Qimonda			(64Mx4)*36	DR	7/21/04
Samsung	M312L2820EG0-CB3	K4H560438E-GCB3	Samsung			(64Mx4)*36	DR	8/3/04
+Smart Modular Technologies	SM12872RDDR6H1BGAI	HYB25D512400BC-6 rev B	Qimonda	P52G184NESZBGAX rev A		(128Mx4)*18	SR	8/26/04
+Smart Modular Technologies	SM12872RDDR6H2BGIC	HYB25D256400CC-6 rev C	Qimonda	P54G184NESZBRCD rev B		(64Mx4)*36	DR	8/31/04
Micron	MT18VDDF12872G-335D3	MT46V128M4FN-6	Micron			(128Mx4)*18	SR	9/3/04
Kingston	KVR333X72RC25/1G	HYB25D256400CC-6 rev C	Qimonda	2025247-001.A00		(64Mx4)*36	DR	9/24/04
+Viking	VI4CR287224DBK L2	K4H560438E-GCB3 rev E	Samsung	0000972B		(64Mx4)*36	DR	9/21/04
+Smart Modular Technologies	SM12872RDDR6H2BGAS	K4H560438E-GCB3 rev E	Samsung	P54G184NESZBRCD rev B		(64Mx4)*36	DR	10/7/04

**Registered, ECC, DDR333 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+Centon Electronics*	TOP02-E150	K4H560438E-GCB3 rev E	Samsung	CPCB/00571 rev G		(64Mx4)*36	DR	10/5/04
+Dataram	DTM63677F	HYB25D256400CC-6 rev C	Qimonda	40599A rev A		(64Mx4)*36	DR	10/6/04
+Smart Modular Technologies	SM12872RDDR6H 8BGIB	HYB25D512800BC-6 rev B	Qimonda	P51G184NE BZBIB1 rev A		(64Mx8)*18	DR	10/22/04
+ATP Electronics	AB28L72Y4BFB3C	HYB25D256400BC-5 rev B	Qimonda	SB184Y04L1		(64Mx4)*36	DR	10/18/04
+TRS	TRS21197	HYB25D256400CC-6 rev C	Qimonda	M0533LA1 rev 1		(64Mx4)*36	DR	11/3/04
+Legacy Electronics Inc.	89S6MDZR-1NDG	HYB25D512400BC-6 rev B	Qimonda	LE18DDF18 44R rev A		(128Mx4)*18	SR	12/2/04
+Ventura Technology Group	D54YCK34SV	K4H560438E-GCB3 rev E	Samsung	V223		(64Mx4)*36	DR	12/13/04
+ATP Electronics	AB28L72L4BFB3C	HYB25D512400BC-6 rev B	Qimonda	SB184L04L1		(128Mx4)*18	SR	1/6/05
Qimonda	HYS72D128321GB R-6-B	HYB25D512800BC-6 B	Qimonda			(64Mx8)*18	DR	1/10/05
+Swissbit	SDR12872K1A32I N-60	HYB25D256400CC-5 rev C	Qimonda	B6R404 rev 1		(64Mx4)*36	DR	1/24/05
Micron	MT36VDDF12872 G-335G3	MT46V64M4FG-6	Micron			(64Mx4)*36	DR	1/20/05
+Smart Modular Technologies	SM12872RDDR6H 1BGIB	HYB25D512400BC-6 rev B	Qimonda	184-22-2		(128Mx4)*18	SR	2/14/05
+ATP Electronics	AB28L72L4BFB3M	MT46V128M4FN-5B rev D	Micron	SB184L04L1		(128Mx4)*18	SR	2/18/05
+ATP Electronics	AB28L72L4BFB3S	K4H510438C-ZCB3 rev C	Samsung	SB184L04L1		(128Mx4)*18	SR	3/8/05
+Ventura Technology Group	D54YFK44MV	MT46V128M4FN-6 rev D	Micron	DR1G472B		(128Mx4)*18	SR	3/10/05
+Legacy Electronics Inc.	89S6JDGM-1NDG	HYB25D256400BC 6 rev B	Qimonda	LE36DDF18 44RRF rev A		(128Mx4)*18	SR	3/3/05
Qimonda	HYS72D128300GB R-6-B	HYB25D512400BC-6 B DRAM date code 0514	Qimonda			(128Mx4)*18	SR	3/21/05
+Dane-Elec	DLD333R072285M	MT46V128M4FN-5B rev D	Micron	DR1G472B		(128Mx4)*18	SR	3/18/05
SimpleTech	ST72E4L128ML-D06E	HYB25D512400BC-6 rev B	Qimonda	01269 rev A		(128Mx4)*18	SR	4/13/05
+Ventura Technology Group	D54YFK44SV	K4H510438C-ZCB3 rev C	Samsung	DR1G472B		(128Mx4)*18	SR	4/11/05
+Wintec Industries	3C954641D-L	HYB25D256400CC-5 rev C	Qimonda	ZK4096M84 RCJB		(64Mx4)*36	DR	4/11/05
+Avant Technology	AVM7228R38C533 3K4-MTG	MT46V64M4FG-6 rev G	Micron	B6R400 rev 1		(64Mx4)*36	DR	4/25/05
+Avant Technology	AVM7228R53C533 3K6-MTD	MT46V128M4FN-6 rev D	Micron	RCE0020-01 rev 1		(128Mx4)*18	SR	4/25/05
Samsung	M312L2920CZ0-CB3	K4H510438C-ZCB3	Samsung		Yes	(128Mx4)*18	SR	5/3/05
Dataram	DTM63694B	K4H510438C-ZCB3 rev C	Samsung	40018A rev A		(128Mx4)*18	SR	5/9/05
Samsung	M312L2820EZ0-CB3	K4H560438E-GCB3	Samsung		Yes	(64Mx4)*36	DR	6/22/05

**Registered, ECC, DDR333 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+Kingston	KVR333D4R25/1G I	K4H560438E-GCB3 rev E	Samsung	2025247-001.A00 na	Yes	(64Mx4)*36	DR	7/21/05
Hynix	HYMD512G726BF4N-J	HY5DU12422B-F-J	Hynix			(64Mx4)*18	DR	7/25/05
Samsung	M312L2923CZ0-CB3	K4H510838C-ZCB3	Samsung		Yes	(64Mx8)*18	DR	8/26/05
+Legacy Electronics Inc.	89L6MDZR-1PDG	BGA128MX4DDR NC na	Legacy	LE18DDF1844R rev A		(128Mx4)*18	SR	9/27/05
+Legacy Electronics Inc.	89B6MDZR-1NDG	K4H510438C-ZCB3 rev C	Samsung	LE18DDF1844R rev A		(128Mx4)*18	SR	10/24/05
Hynix	HYMD512G726CFP4N-J	HY5DU12422CFP-J	Hynix			(128Mx4)*18	SR	10/24/05
Samsung	M312L2920CZ3-CB3	K4H510438C-ZCB3	Samsung		Yes	(128Mx4)*18	SR	11/15/05
Samsung	M312L2923CZ3-CB3	K4H510838C-ZCB3	Samsung		Yes	(64Mx8)*18	DR	11/15/05
Samsung	M312L2820EG3-CB3	K4H510438B-GCB3	Samsung			(64Mx4)*36	DR	11/15/05
Samsung	M312L2820EZ3-CB3	K4H510438B-ZCB3	Samsung		Yes	(64Mx4)*36	DR	11/15/05
Qimonda	HYS72D128321HBR-6-C	HYB25D512800CF-6	Qimonda		Yes	(64Mx8)*18	DR	1/31/06
Qimonda	HYS72D128300HBR-6-C	HYB25D512400CF-6	Qimonda		Yes	(128Mx4)*18	SR	1/31/06
TRS	TRS21196	HYB25D256400BC-6 rev B	Qimonda	M0533LA1 rev 1		(64Mx8)*18	DR	05/24/06
Kingston	KVR333D4R25/1G I	HYB25D256400CF-5 rev C	Qimonda	2025247-001.A00 na	Yes	(64Mx8)*18	DR	05/26/06
TRS	TRS21229	HYB25D512400BC-6 rev B	Qimonda (Infineon)	M0545LA1 rev 1		(128Mx4)*18		6/07/06
Kingston	KVR333D4R25/2G I	K4H510438C-ZCB3 rev C	Samsung	2025294-001.A00 na	Yes	(128Mx4)*18		7/25/06
Kingston	KVR333S4R25/1GI	K4H510438C-ZCB3 rev C	Samsung	2025324-001.A00 na	Yes	(128Mx4)*18	SR	8/23/06
Kingston	KVR333S4R25/1GI	K4H510438C-ZCCC rev C	Samsung	2025324-001.A00 na	Yes	(128Mx4)*18	SR	10/9/06
Kingston	KVR333S4R25/1GI	HYB25D512400CF-5 rev C	Qimonda	2025324-001.A00 na	Yes	(128Mx4)*18	SR	5/1/07
Kingston	KVR333S4R25/1GI	HYB25D512400BF-5 rev B	Qimonda	2025324-001.A00 na	Yes	(128Mx4)*18	SR	9/26/07

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Micron	MT18HTF12872Y-40EA2	MT47H64M8BT-5E	Micron		Yes	(128Mx4)*18	SR	6/6/05
Qimonda	HYS72T128000HR-5-A	HYB18T512400AF5	Qimonda		Yes	(128Mx4)*18	SR	5/12/05
Samsung	M393T2950BG0-CCC	K4T51043QB-GCCC	Samsung			(128Mx4)*18	SR	5/12/05
Samsung	M393T2950CZ0-CCC	K45T1043QC-ZCCC	Samsung		Yes	(128Mx4)*18	SR	7/8/05
Samsung	M393T2953BG0-CCC	K4T510830B-GCCC	Samsung			(64Mx8)*18	DR	6/27/05

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Samsung	M393T2953BZ0-CCC	K4T51083QB-ZCCC	Samsung		Yes	(64Mx8)*18	DR	6/27/05
Samsung	M393T2953CZ0-CCC	K4T510830C-ZCCC	Samsung		Yes	(64Mx8)*18	DR	7/25/05
Micron	MT18HTF12872Y-40EB3	MT47H64M8BT-5E	Micron		Yes	(128Mx4)*18	SR	7/25/05
Qimonda	HYS72T128020HR-5-A	HYB18T512800AF5-A	Qimonda		Yes	(64Mx8)*18	DR	7/25/05
Samsung	M393T2950BZ0-CCC	K4T51043QB-ZCCC	Samsung		Yes	(128Mx4)*18	SR	8/3/05
+Smart Modular Technologies	SB1287RDR2124-3-5-H	HY5PS12421FP-E3 A 1st Generation	Hynix	E72369 na		(128Mx4)*18	SR	08/19/05
+ATP Electronics	AH28K72M4BHC4S	K4T51043QC-ZCCC rev C	Samsung	SH240M04K1 na		(128Mx4)*18	SR	8/29/05
+Smart Modular Technologies	SB1287RDR2124-35IA	HYB18T512400AF5 rev A	Qimonda	PB54G240NESU BRCC1 rev A		(128Mx4)*18	SR	8/29/05
+Legacy Electronics Inc.	S512872M20A-50A	HYB18T512400AF(C)5 rev A	Qimonda	LE18DD2F2404 RRH rev A		(128Mx4)*18	SR	9/1/05
Virtium Technology Inc*	VL393T2953-CCS	K4T51083QC-ZCD5 rev C	Samsung	D2R872		(64Mx8)*18	DR	9/19/05
+Kingston	KVR400D2S4R3/1GI	E5104AE-5C-E rev E	Elpida	2025248-001.B00		(128Mx4)*18	SR	9/27/05
Virtium Technology Inc	VL393T2950-CCM	MT47H128M4BT-37E rev A	Micron	D2R472		(128Mx4)*18	SR	9/22/05
Samsung	M393T2950CZ3-CCC	K4T51043QC-ZCCC	Samsung		Yes	(128Mx4)*18	SR	9/30/05
+Dataram	DTM63310A	HYB18T512400AF5 rev A	Qimonda	40011A rev A		(128Mx4)*18	SR	10/6/05
+Kingston	KVR400D2S8R3/1GI	HYB18T1G800AF-5 rev A	Qimonda	2025263-001.C00		(128Mx4)*18	SR	9/29/05
+Smart Modular Technologies	SB1287RDR2124-3-5-E	E5104AB-4A-E rev B	Elpida	Z10 026A na		(128Mx4)*18	SR	10/3/05
+Ventura Technology Group	D2-54KF53SV-333	K4T51043QB-ZCCC rev B	Samsung	D2R472		(128Mx4)*18	SR	9/30/05
+Legend	L12723C7-RCAH2HBF	HY5PS12821F-E3 rev A	Hynix	B62RRCA rev A		(64Mx8)*18	DR	11/3/05
Hynix	HYMP512R724-E3	HY5PS12421-F-E3	Hynix			(128Mx4)*18	SR	10/24/05
Samsung	M393T2953CZ3-CCC	K4T510830C-ZCCC	Samsung		Yes	(64Mx8)*18	DR	11/4/05
+Kingston	KVR400D2S4R3/1GI	HYB18T512400AF5 rev A	Qimonda	2025248-001.B00 na		(128Mx4)*18	SR	12/7/05
Nanya Technology Corporation	NT1GT72U4PA0BV-5A	NT5TU128M4AE-5A rev A	Nanya	NTPCB00019 (0519, 0515) na		(128Mx4)*18	SR	1/6/06
Hynix	HYMP512R72P4-E3	HY5PS12421FP-E3	Hynix		Yes	(128Mx4)*18	SR	1/10/06
Hynix	HYMP512R72P8-E3	HY5PS12821FP-E3	Hynix			(64Mx8)*18	DR	11/15/05
+Kingston	KVR400D2S4R3/1GI	HYB18T512400AF3 7 rev A	Qimonda	2025248-001.B00 na	Yes	(128Mx4)*18	SR	1/18/06
+Smart Modular Technologies	SG1287RDR2648-35IA	HYB18T512800AF3 7 rev A	Qimonda	PG58G240NEB UB2RB rev A		(64Mx8)*18	DR	1/23/06

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Hynix	HYMP112R72P8-E3	HY5PS1G831FP-E3	Hynix		Yes	(128Mx8)*9		1/31/06
Hynix	HYMP512R72BP4-E3	HY5PS12421BFP-E3	Hynix		Yes	(128Mx4)* 18	SR	1/31/06
Hynix	HYMP512R72BP8-E3	HY5PS12821BFP-E3	Hynix		Yes	(64Mx8)*18	DR	1/31/06
+Legacy Electronics Inc.	B517M4C2AHA-50	K4T51043QC-ZCCC rev C	Samsung	LE18DD2F2404 RRH rev A		(128Mx4)* 18	SR	2/9/06
+Wintec Industries	39S931341A-L	HYB18T512400AF5 rev A	Qimonda	D2R472	Yes	(128Mx4)* 18	SR	2/16/06
SimpleTech	SL72P4M128M8M-B05AYU	HYB18T512400AF5 rev A	Qimonda	01235 rev B	Yes	(128Mx4)* 18	SR	2/23/06
+Smart Modular Technologies	SG1287RDR264835SC	K4T51083QC-ZCD5 rev C	Samsung	PG58G240NEBUB2RB rev A	Yes	(64Mx8)*18	DR	3/21/06
Kingston	KVR400D2S8R3/1GI	E1108AA-5C-E rev A	Elpida	2025263-001.C00 na	Yes	(128Mx8)*9		05/12/06
ATP Electronics	AH28K72M4BHC4S	K4T51043QC-ZCCC rev C	Samsung	SH240M04K2 na	Yes	(128Mx4)* 18	SR	05/15/06
Apacer	75.072A1.G00	K4T51043QC-ZCD5 rev C	Samsung	48.16189.011 rev 1	Yes	(128Mx4)* 18	SR	05/24/06
Kingston	KVR400D2S4R3/1GI	NT5U128M4AE-5A rev A	Nanya	2025248-001.B00 na	Yes	(128Mx4)* 18	SR	6/7/06
Smart Modular Technologies	SG1287RDR212435NA	NT5TU128M4AE-5A rev A	Nanya	NTPCB00019P	Yes	(128Mx4)* 18	SR	7/5/06
TRS	TRS31267	K4T51043QC-ZCCC rev C	Samsung	M0549LA1 rev 1	Yes	(128Mx4)* 18	SR	6/23/06
Super Talent Electronics	T400RA1G4/S1GTR4BHS	K4T51043QC-ZCD5 rev C	Samsung	DR20418 rev H1.01	Yes	(128Mx4)* 18	SR	8/8/06
Super Talent Electronics	T400RB1G/S1GTR8CHS	K4T51083QC-ZCD5 rev C	Samsung	DR20818 rev G1.01	Yes	(64Mx8)*18	DR	8/15/06
TRS	TRS31265X	HYB18T512400AF5 rev A	Qimonda (Infineon)	M0549LA1 rev 1	Yes	(128Mx4)* 18	SR	9/8/06
Kingston	KVR400D2S4R3/1GI	E5104AG-5C-E rev G	Elpida	2025248-001.B00 na	Yes	(128Mx4)* 18	SR	10/12/06
Kingston	KVR400D2S8R3/1GI	E1108AB-6E-E rev B	Elpida	2025263-001.C00 na	Yes	(128Mx8)*9		11/27/06
Micron	MT18HTF12872Y-40ED6	MT47H128M4B6-37E:D	Micron		Yes	(128Mx4)* 18	SR	1/11/07
TRS	TRS31277X	E5104AG-5C-E rev G	Elpida	M0549LA1 rev 1	Yes	(128Mx4)* 18	SR	3/6/07
Kingston	KVR400D2S8R3/1GI	MT47H128M8HQ-3 rev E	Micron	2025263-001.C00 na	Yes	(128Mx8)*9		4/25/07
Kingston	KVR400D2S4R3/1GI	E5104AHSE-6E-E rev H	Elpida	2025248-001.B00 na	Yes	(128Mx4)* 18	SR	5/3/07
Kingston	KVR400D2S4R3/1GI	E5104AHSE-6E-E rev H	Elpida	2025248-001.B00 na	Yes	(128Mx4)* 18	SR	5/4/07
Smart Modular Technologies	SG1287RDR212435IB	HYB18T512400BF37 rev B	Qimonda	PG54G240NESUBRCC1 rev A	Yes	(128Mx4)* 18	SR	10/23/07
Kingston	KVR400D2S4R3/1GI	NT5TU128M4BE-3C rev B	Nanya	2025248-001B00	Yes	(128Mx4)* 18	SR	12/20/07

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Kingston	KVR400D2S4R3/1GI	HYB18T512400B2 F25F rev B2	Qimonda	2025248-001.B00	Yes	128M x 4	1	06/02/08
Kingston	KVR400D2S8R3/1GI	E1108ACBG-8E-E rev C	Elpida	2025263-001.C00	Yes	128M x 8	1	06/12/08
Kingston	KVR400D2S4R3/1GI	HYB18T512400B2 F25F rev B2	Qimonda	2025248-001.B00	Yes	128M x 4	1	06/04/08
Kingston	KVR400D2S8R3/1GI	E1108ACBG-8E-E rev C	Elpida	2025263-001.C00	Yes	128M x 8	1	06/12/08

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Server Board SE7520BD2
Registered, ECC, DDR266 DIMM Modules
2GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+TRS	TRS21155	HYB25D512400AT-7 rev A	Qimonda	M0531LA1 rev 1		(128Mx4)*36	DR	9/7/04
+Ventura Technology Group	D56WXK28SV	K4H510438B-TCB3 rev B	Samsung	V213		(128Mx4)*36	DR	10/15/04
Kingston	KVR266X72RC25 /2G	K4H510438B-TCB0 rev B	Samsung	2025148-001.A00		(128Mx4)*36	DR	11/22/04
+Viking	VI4CR567224EY HL3	K4H510438B-TCB3 rev B	Samsung	03-0307 rev B		(128Mx4)*36	DR	12/17/04
+Dataram	DTM63710A	HYB25D512400BE-7 rev B	Qimonda	40028A rev A		(128Mx4)*36	DR	1/20/05
+ATP Electronics	AB56L72T4SHB0 S	K4H510438B-TCB3 rev B	Samsung	SB184T04L3		(128Mx4)*36	DR	1/28/05
Samsung	M312L5628BT0-CB0	K4H1G0638B-TCB0	Samsung			(128Mx4)*36	DR	6/20/05
+TRS	TRS21218	HYB25D512400BE-7 rev B	Qimonda	M0531LA1 rev 1	Yes	(128Mx4)*36	DR	7/28/05
+TRS	TRS21218	HYB25D512400BE-7 rev B	Qimonda	M0531LA1 rev 1		(128Mx4)*36	DR	07/28/05
Samsung	M312L5628CU0-CB0	K4H1G0638C-UCB0	Samsung		Yes	(128Mx4)*36	DR	9/6/05
Micron	MT36VDDF25672 G-265D2	MT46V128M4FN	Micron			(128Mx4)*36	DR	9/23/05
Smart Modular Technologies	SG25672RDDR3 H1BGSC	K4H510438C-ZCB3 rev C	Samsung	PG54G184N ESZB1RF rev A	Yes	(128Mx4)*36		6/12/06

Registered, ECC, DDR333 DIMM Modules
2GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Micron	MT36VDDF25672 G-335D2	MT46V128M4FN	Micron			(128Mx4)*36	DR	8/3/04
+Dataram	DTM63680F	HYB25D512400BF-6 rev B	Qimonda	40020A rev A		(128Mx4)*36	DR	8/27/04
+Smart Modular Technologies	SM25672RDDR6H 2BGAI	HYB25D512400BC-6 rev B	Qimonda	P54G184NE SZB1RF rev A		(128Mx4)*36	DR	9/23/04
+Smart Modular Technologies	SM25672RDDR6H 2BGBI	HYB25D512400BC-6 rev B	Qimonda	184-25-2		(128Mx4)*36	DR	1/11/05
+ATP Electronics	AB56L72Z4BFB3C	HYB25D512400BC-6 rev B	Qimonda	SB184Z04L1		(128Mx4)*36	DR	1/26/05
+ATP Electronics	AB56L72Z4BFB3S	K4H510438C-ZCB3 rev C	Samsung	SB184Z04L1		(128Mx4)*36	DR	2/25/05
Qimonda	HYS72D256320GB R-6-B	HYB25D512400BC-6 B	Qimonda			(128Mx4)*36	DR	3/2/05

**Registered, ECC, DDR333 DIMM Modules
2GB Size (256M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
+Kingston	KVR333D4R25/2 GI	HYB25D512400B C-6 rev B	Qimonda	2025294-001.A00		(128Mx4)*36	DR	4/6/05
+Wintec Industries	35964741-L	HYB25D512400B C-6 rev B	Qimonda	85616658		(128Mx4)*36	DR	4/15/05
+Avant Technology	AVM7256R53C53 33K7-MTD	MT46V128M4FN-6 rev D	Micron	B6R404 rev 1		(128Mx4)*36	DR	5/6/05
+Smart Modular Technologies	SG25672RDDR6 H2BGSC	K4H510438C-ZCB3 rev C	Samsung	PG54G184 NESZB1RF rev A		(128Mx4)*36	DR	5/19/05
+Legacy Electronics	8AB6MDGM-1NDG	K4H510438C-ZCB3 rev C	Samsung	LE36DDF18 44RRF rev B		(128Mx4)*36	DR	08/04/05
+Viking	VR4CR567224EB KL1	HYB25D512400C F-6 rev C	Qimonda	0001010B rev B		(128Mx4)*36	DR	8/29/05
Samsung	M312L5720CZ0-CB3	K4H510438C-ZCB3	Samsung		Yes	(128Mx4)*36	DR	9/21/05
+Kingston	KVR333D4R25/2 GI	MT46V128M4FN-6 rev D	Micron	2025294-001.A00 na		(128Mx4)*36	DR	10/4/05
Samsung	M312L5720CZ3-CB3	K4H510438C-ZCB3	Samsung		Yes	(128Mx4)*36	DR	11/15/05
Qimonda	HYS72D256320H BR-6-C	HYB25D512400C F-6	Qimonda		Yes	(128Mx4)*36	DR	1/31/06
Kingston	KVR333D4R25/2 GI	HYB25D512400C F-5 rev C	Qimonda	2025294-001.A00 na	Yes	(128Mx4)*36	DR	4/17/07
Kingston	KVR333D4R25/2 GI	HYB25D512400BF -5 rev B	Qimonda	2025294-001.A00 na	Yes	(128Mx4)*36	DR	9/28/07
Qimonda	HYS72T256000H R-5-A	HYB18T1G400AF-5	Qimonda		Yes	(256Mx4)*18	SR	5/4/05
Qimonda	HYS72T256220H R-5-A	HYB18T512400AF 5	Qimonda		Yes	(128Mx4)*36	DR	6/6/05
Hynix	HYMP125R724-E3	HY5PS1G431F-E3	Hynix			(256Mx4)*18	SR	6/21/05
Micron	MT36HTF25672Y -40EB1		Micron		Yes			7/8/05
Samsung	M393T5660MZ0-CCC	K4T1G044QM-ZCCC	Samsung		Yes	(256Mx4)*18	SR	6/8/05
Micron	MT18HTF25672Y -40EA2		Micron		Yes	(256Mx4)*18	SR	7/25/05
+Kingston	KVR400D2D8R3/2GI	HYB18T1G800AF-5 rev A	Qimonda	2025302-001.A00 na		(128Mx8)*18	DR	8/24/05
+Smart Modular Technologies	SG2567RDR2128 35IA	HYB18T512400AF 5 rev A	Qimonda	PG52G240 NESUB1RJ rev A		(128Mx4)*36	DR	8/15/05
+Legacy Electronics Inc.	S525672M20A-50A	HYB18T512400AF 5 rev A	Qimonda	LE36DD2F2 404RRJ rev B		(128Mx4)*36	DR	8/12/05

**Registered, ECC, DDR2-400 DIMM Modules
2GB Size (256M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Samsung	M393T5750CZ0-CCC	K45T1043QC-ZCCC	Samsung		Yes	(128Mx4)*36	DR	9/20/05
+Smart Modular Technologies	SB2567RDR212835IA	HYB18T512400AF5 rev A	Qimonda	PB52G240NESUB1RJ rev A		(128Mx4)*36	DR	10/14/05
+Smart Modular Technologies	SG2567RDR21283-5-H	HY5PS1G421MP-E3 rev A	Hynix	(0504-5,-3,-1),(0518-1,-2,-3,-4,-6),(0516-1,-3)	Yes	(128Mx4)*36	DR	10/20/05
Hynix	HYMP125R72P4-E3	HY5PS1G431FP-E3	Hynix			(256Mx4)*18	SR	10/24/05
Samsung	M393T5750CZ3-CCC	K45T1043QC-ZCCC	Samsung		Yes	(128Mx4)*36	DR	11/4/05
Samsung	M393T5660MZ3-CCC	K4T1G044QM-ZCCC	Samsung		Yes	(256Mx4)*18	SR	11/4/05
+Kingston	KVR400D2D4R3/2GI	HYB18T512400AF5 rev A	Qimonda	2025292-001.B00 na		(128Mx4)*36	DR	12/16/05
+Legacy Electronics Inc.	B527M4C2BJA-50	K4T51043QC-ZCCC rev C	Samsung	LE36DD2F2404RRJ rev B		(128Mx4)*36	DR	12/22/05
Nanya Technology Corporation	NT2GT72U4NA1BV-5A	NT5TU128M4AE-5A rev A	Nanya	NTPCB00037P (0514) na		(128Mx4)*36	DR	1/12/06
Samsung	M393T5660AZ3-CCC	K4T1G044QA-ZCCC	Samsung		Yes	(256Mx4)*18	SR	12/13/05
Hynix	HYMP125R72P8-E3	HY5PS1G831FP-E3	Hynix		Yes	(128Mx8)*18		1/31/06
Hynix	HYMP525R72BP4-E3	HY5PS12421BFP-E3	Hynix		Yes	(128Mx4)*36	DR	1/31/06
+Legend	L25723C7-R41H2W2F	HY5PS1G421MP-E3 rev 1st Gen.	Hynix	0536	Yes	(256Mx4)*18	SR	3/2/06
Kingston	KVR400D2D4R3/2GI	HYB18T512400AF37 rev A	Qimonda (Infineon)	2025292-001.B00 na	Yes	(128Mx4)*36	DR	05/01/06
Kingston	KVR400D2D8R3/2GI	E1108AA-5C-E rev A	Elpida	2025302-001.A00 na	Yes	(128Mx8)*18		05/18/06
Apacer	75.A72A1.G00	K4T51043QC-ZCCC rev C	Samsung	48.1A189.012 rev 2	Yes	(128Mx4)*36		6/22/06
Kingston	KVR400D2D4R3/2GI	NT5TU128M4AE-5A rev A	Nanya	2025292-001.B00 na	Yes	(128Mx4)*36		6/20/06
Super Talent Electronics	T400RB2G4/S2GTR4CHS	K4T51043QC-ZCD5 rev C	Samsung	BA2RRCJ na	Yes	(128Mx4)*36	DR	8/18/06
Kingston	KVR400D2D4R3/2GI	E5104AG-5C-E rev G	Elpida	2025292-001.B00 na	Yes	(128Mx4)*36	DR	10/11/06
Smart Modular Technologies	SG2567RDR212435NB	NT5TU128M4BE-3C rev B	Nanya	PG52G240NESUB3RJ rev A	Yes	(128Mx4)*36	DR	12/6/06
Kingston	KVR400D2D8R3/2GI	E1108AB-6E-E rev B	Elpida	2025302-001.A00 na	Yes	(128Mx8)*18		12/13/06
Netlist, Inc.	NLD257D21203FD32KIB	HYB18T512400BF-3S rev B	Qimonda	0298-10B-KCC rev B	Yes	(128Mx4)*36	DR	4/9/07
Kingston	KVR400D2D8R3/2GI	MT47H128M8HQ-3 rev E	Micron	2025302-001.A00 na	Yes	(128Mx8)*18		4/17/07
+Legend	L25723C7-R41H2W2F	HY5PS1G421MP-E3 rev 1st Gen.	Hynix	0536	Yes	(256Mx4)*18	SR	3/2/06
Kingston	KVR400D2D4R3/2GI	HYB18T512400AF37 rev A	Qimonda (Infineon)	2025292-001.B00 na	Yes	(128Mx4)*36	DR	05/01/06
Kingston	KVR400D2D8R3/2GI	E1108AA-5C-E rev A	Elpida	2025302-001.A00 na	Yes	(128Mx8)*18		05/18/06

Registered, ECC, DDR2-400 DIMM Modules 2GB Size (256M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Kingston	KVR400D2D4R3/2GI	E5104AHSE-6E-E rev H	Elpida	2025292-001.C00 na	Yes	(128Mx4)*36	DR	5/8/07
Smart Modular Technologies	SG2567RDR212435IB	HYB18T512400BF3S rev B	Qimonda	PG52G240 NESUB3RJ rev A	Yes	(128Mx4)*36	DR	10/1/07
Smart Modular Technologies	SG2567RDR212435SE	K4T51043QE-ZCE6 rev E	Samsung	PG52G240 NESUB3RJ rev A	Yes	(128Mx4)*36	DR	10/19/07
Kingston	KVR400D2D4R3/2GI	NT5TU128M4BE-3C rev B	Nanya	2025292-001.C00 na	Yes	(128Mx4)*36	DR	1/4/08
Kingston	KVR400D2D8R3/2GI	HY5PS1G831CFP-Y5 rev C	Hynix	2025302001.A00 na	Yes	(128Mx8)*18		2/28/08
Kingston	KVR400D2D4R3/2GI	HYB18T512400AF37 rev A	Qimonda	2025292-001.C00 rev C	Yes	(128Mx4)*36		4/18/08
Kingston	KVR400D2D4R3/2GI	HYB18T512400B2F25F rev B2	Qimonda	2025292-001.C00	Yes	128M x 4	DR	06/04/08
Kingston	KVR400D2D4R3/2GI	HYB18T512400B2F25F rev B2	Qimonda	2025292-001.C00	Yes	128M x 4	DR	06/02/08
Kingston	KVR400D2D8R3/2GI	E1108ACBG-8E-E rev C	Elpida	2025302-001.A00	Yes	128M x 8	DR	06/23/08

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Server Board SE7520BD2 Registered, ECC, DDR266 DIMM Modules 4GB Size (256M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Micron	MT36VDDT51272G-265A2	MT46V256M4TG-75A	Micron			(256Mx4) *36	DR	4/15/05
Samsung	M312L5128MT0-CB0	K4H2G0638M-TCB0	Samsung			(256Mx4) *36	DR	8/29/05
Registered, ECC, DDR2-400 DIMM Modules 4GB Size (256M x 72)								
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Lead-Free	DRAM Organization	Rank	Date
Qimonda	HYS72T512022HR-5-A	HYB18T2G402AF-5-A	Qimonda		Yes	(256Mx4) *36	DR	11/1/05
Hynix	HYMP351R72MP4-E3	HY5PS2G431MP-E3	Hynix		Yes	(256Mx4) *36	DR	11/17/05
Smart Modular Technologies	SG5127RDR225635ART	HYB18T1G400AF-5 rev A	Qimonda	XG58G240NESUB1TK rev A	Yes	(256Mx4) *36	DR	1/9/07
Kingston	KVR400D2D4R3/4GI	E1108ABSH-E rev B	Elpida	Z10077 na	Yes	(256Mx4) *36	DR	2/23/07
Legacy Electronics Inc.	M547RAE20LA-50R	MT47H256M4HQ-3 rev E	Micron	D2R24L rev E	Yes	(256Mx4) *36	DR	4/23/07

Modules in bold text do not contain Lead.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

4. Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpinc.com/	Tel (1) 408-732-5000, ext 5858 Fax 408-732-5893 sales@atpusa.com
ATP Electronics -- Taiwan Inc.	http://www.atpinc.com/	Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 phenke@dataram.com
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.heacom/	
Qimonda	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itauc.com.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Gary Ridenour, 949-498-9600, Ext 350 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/http://silicon.micron.com/mktg/mbqual/qual_data.cfm	
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com

Vendor Name	Web URL	Vendor Direct Sales Info
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com
Peripheral Enhancements Samsung	http://www.peripheral.com/ http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	www.smartm.com/channel/hpc/	Gene Patino (949) 439-6167 Gene.Patino@Smartm.com
Swissbit	http://www.swissbit.com	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 tony.cerreta@swissbitna.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http://www.certified-memory.com http://www.certified-memory.de	Vendor Direct Sales Info: Andreas Gruendl Tel: +49.89.945532-34 Fax: +49.89.945532-41 Andreas.gruendl@trs-eu.com
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Sam Lewis 760 724-8700 ext. 103
Viking InterWorks	http://www.vikinginterworks.com	Adrian Proctor Tel: 949-643-7255 adrian.proctor@sanmina-sci.com
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

5. CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Qualification Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

IMPORTANT NOTE

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each Rank on the memory module. Mixing of dissimilar memory manufacturer devices or dissimilar memory device speeds is *not* recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with the Intel® Server RAID Controller. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the Intel® Server RAID Controller. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server RAID Controller product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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